

**In the Claims:**

**Please enter the following amended claims 1, 9, 11 and 19:**

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A<sup>1</sup> 1. (Once Amended) A structure comprising:  
a laminate substrate having a top surface for receiving a semiconductor die;  
an antenna situated on a bottom surface of said laminate substrate, said antenna  
being suitable for connection to said semiconductor die;  
a laminate substrate reference pad in said laminate substrate, said laminate substrate  
reference pad situated over said antenna;  
at least one laminate substrate reference via situated at a side of said antenna.

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A<sup>2</sup> 9. (Once Amended) The structure of claim 1 wherein a shape of said antenna  
is selected from the group consisting of a square shape, a rectangular shape, a slot line  
pattern, a meander line pattern, and a patch pattern.

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A<sup>3</sup> 11. (Once Amended) A structure comprising:  
a laminate substrate having a top surface for receiving a semiconductor die;  
an antenna situated on a bottom surface of said laminate substrate, said antenna  
being suitable for connection to said semiconductor die;  
a laminate substrate reference pad in said laminate substrate, said laminate substrate  
reference pad situated over said antenna;

A3  
Cont.

a plurality of laminate substrate reference vias, each of said plurality of laminate substrate reference vias situated at a side of said antenna.

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A4

19. (Once Amended) The structure of claim 11 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

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